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United States Patent [19]

Steen, Jr. et al.

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[54] **HEAT SINK CLIP FOR SURFACE-MOUNT INTEGRATED CIRCUIT**

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[73] Assignee: **Motorola, Inc.**, Schaumburg, Ill.

[**] Term: **14 Years**

[21] Appl. No.: **754,133**

[22] Filed: **Sep. 3, 1991**

[52] **U.S. Cl.** **D13/179**

[58] **Field of Search** D13/179; 165/80.2; 257/713, 718; 361/383, 386; 174/16.3

[56] **References Cited**

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Primary Examiner—Wallace R. Burke
Assistant Examiner—Joel Sincavage
Attorney, Agent, or Firm—James A. Coffing

[57] CLAIM

The ornamental design for a heat sink clip for surface-mount integrated circuit, as shown and described.

DESCRIPTION

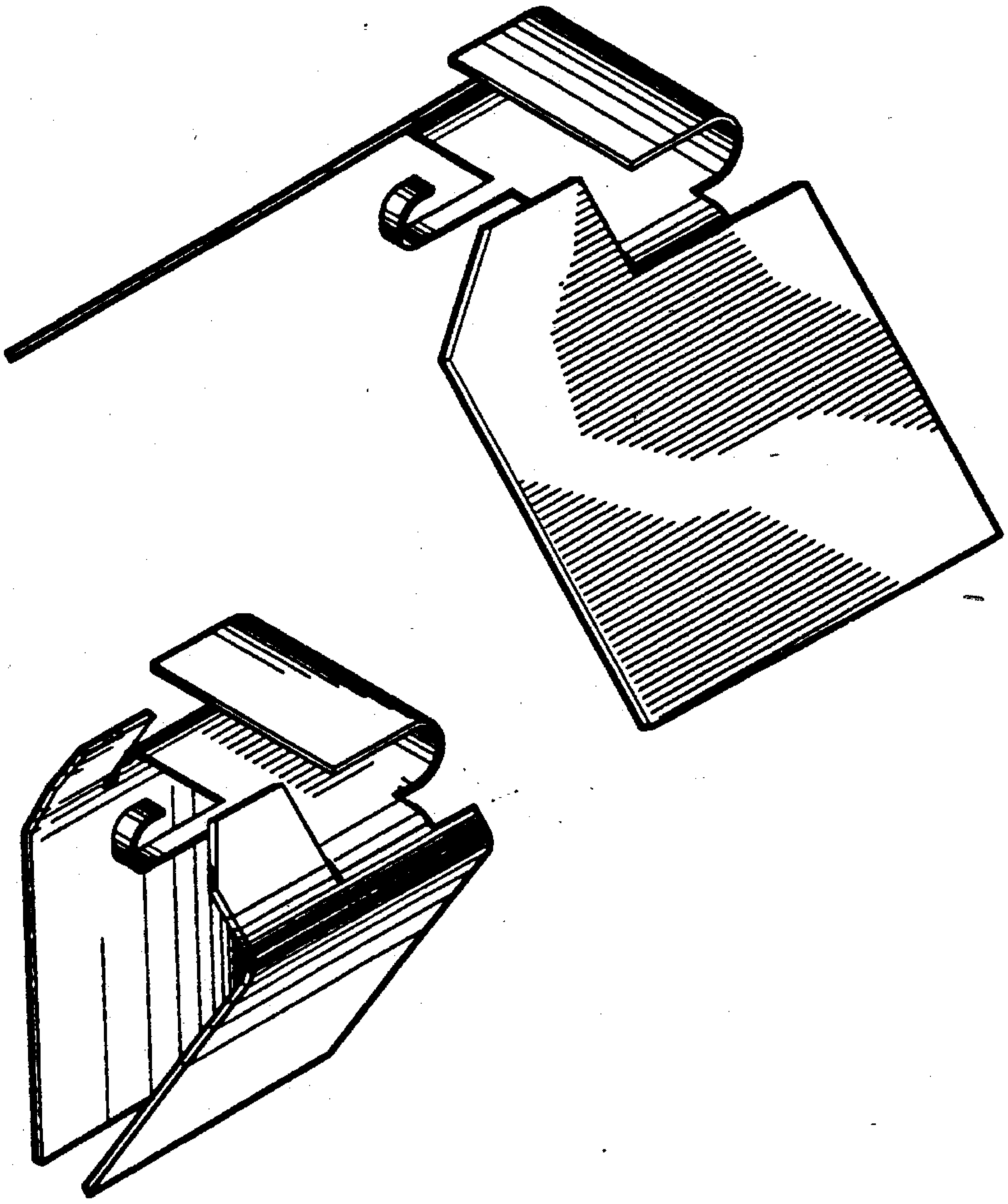
FIG. 1 is a front, top, and right side perspective view showing our new design for a heat sink clip for surface-mount integrated circuit;

FIG. 2 is a left elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a bottom plan view thereof; and,

FIG. 5 is a front, top, and right side perspective view showing an alternate embodiment for a heat sink clip for surface mount integrated circuit, the front, top, and left side perspective view being a mirror image.



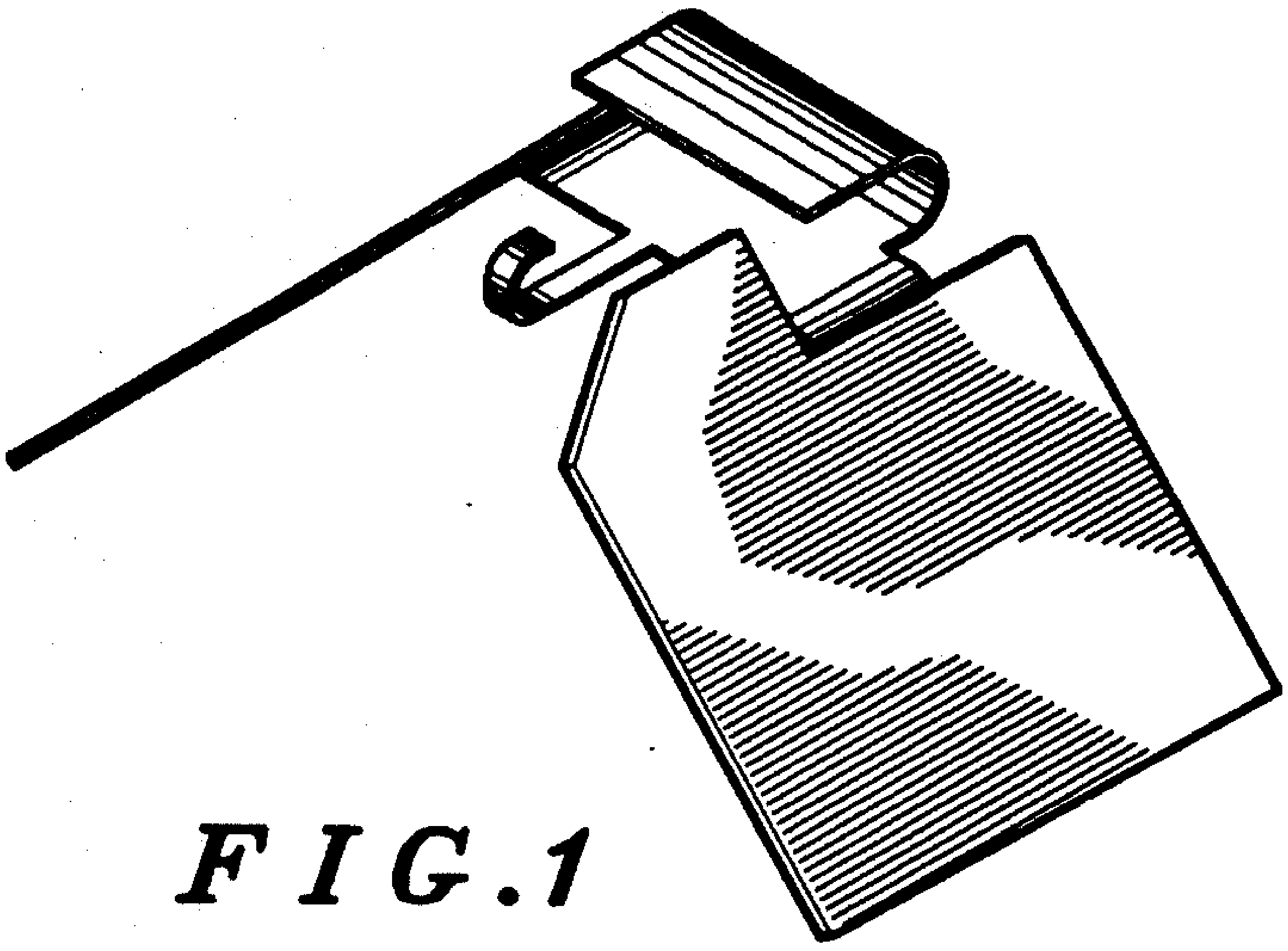


FIG.1

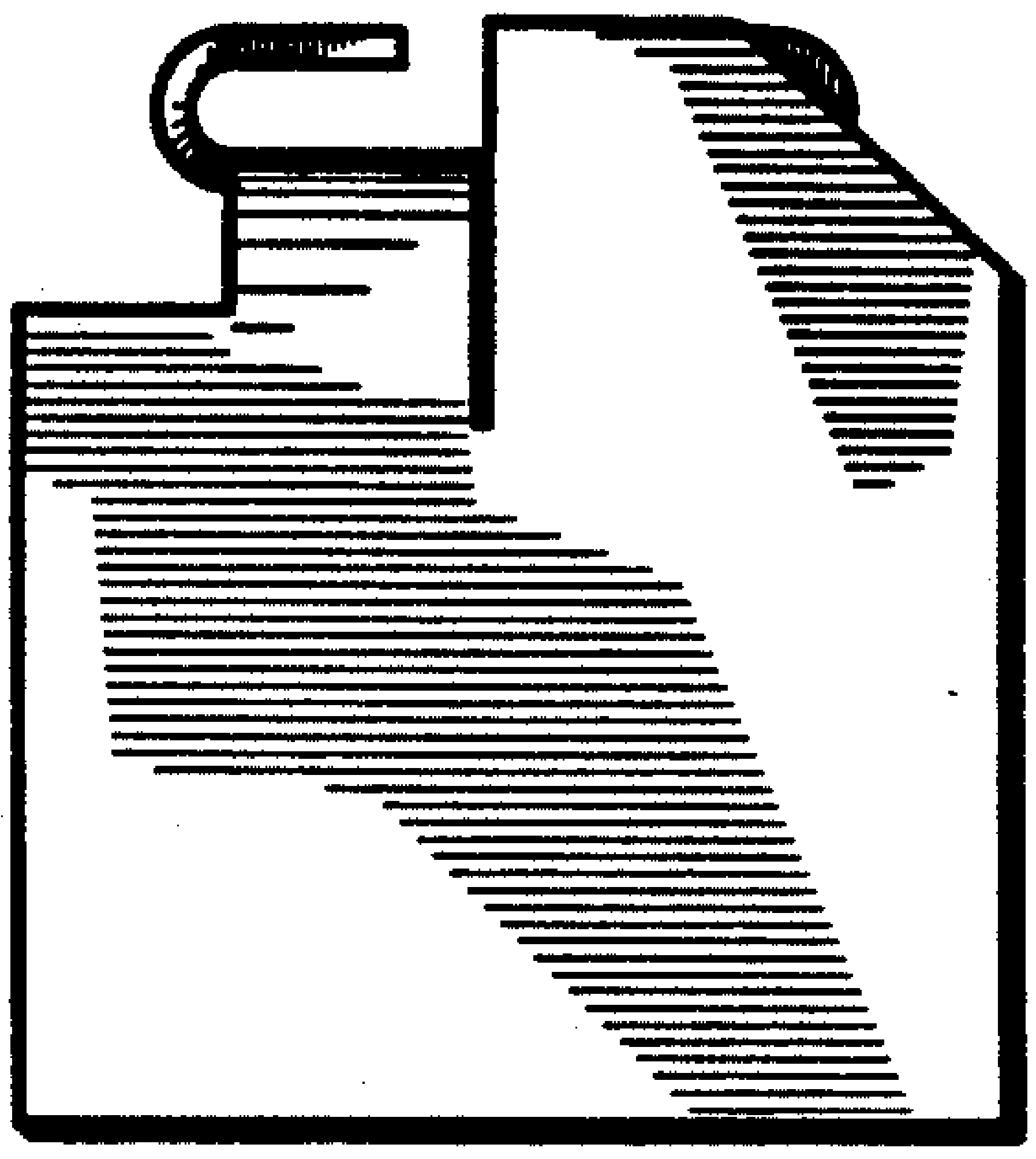


FIG.2

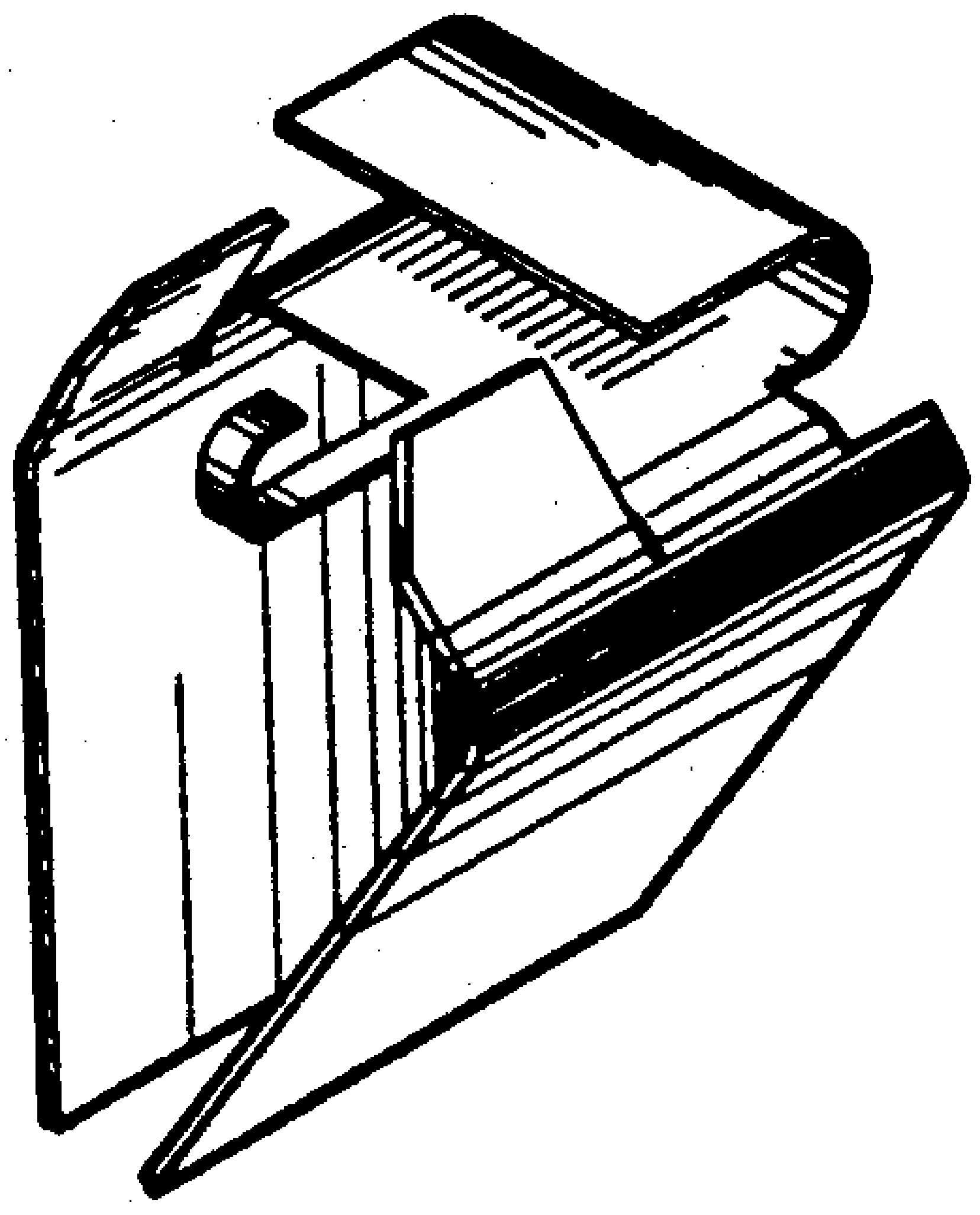


FIG.5

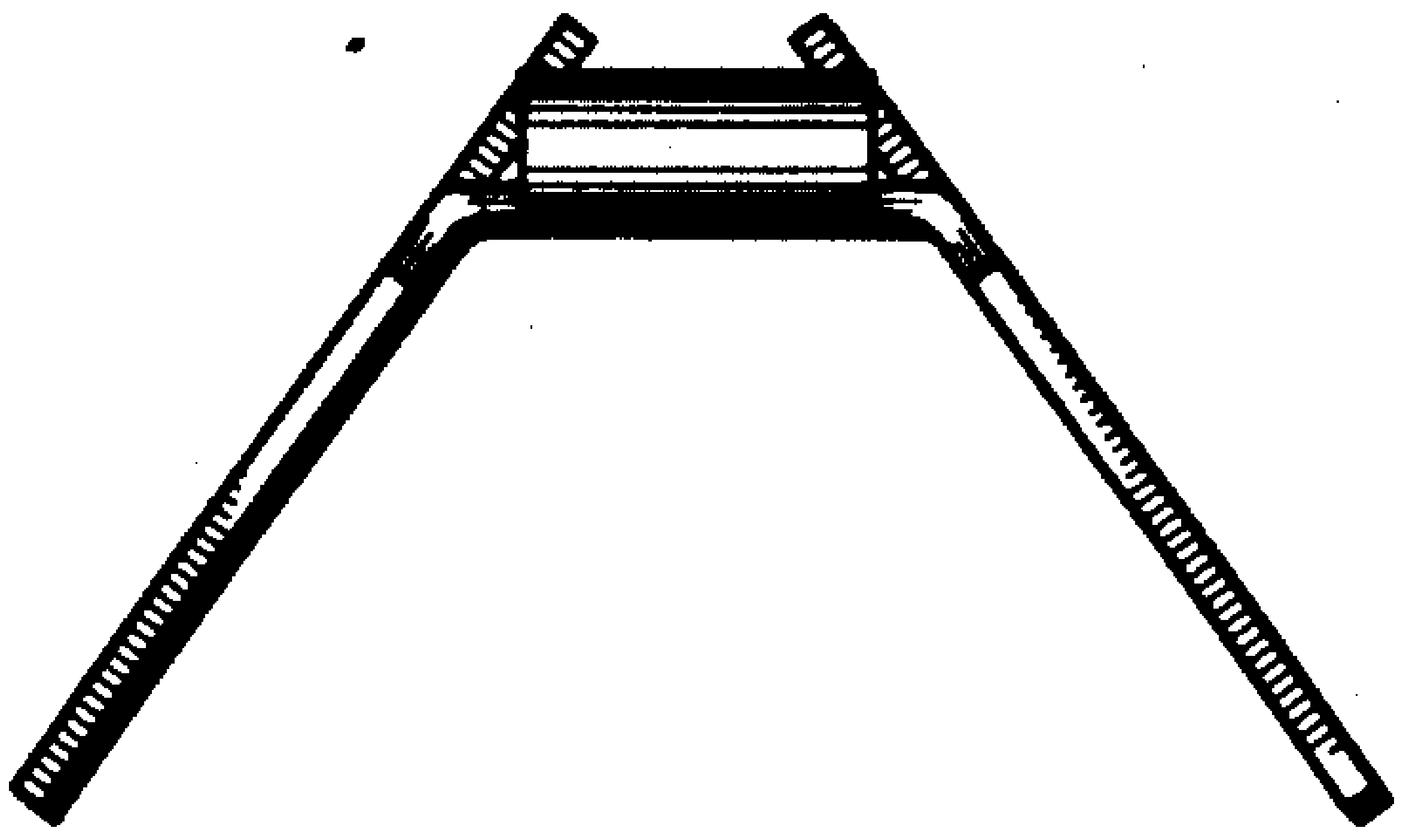


FIG.3

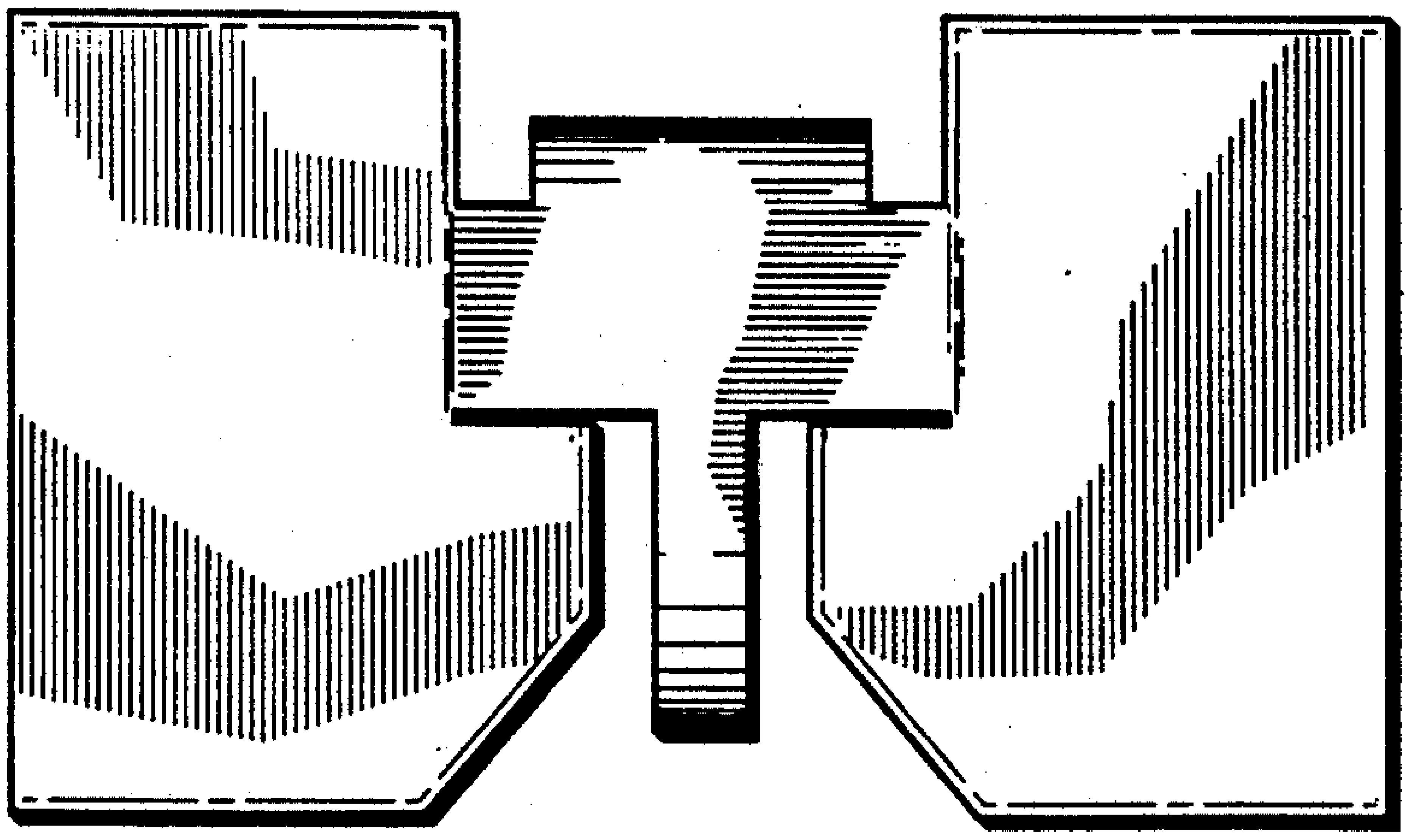


FIG.4